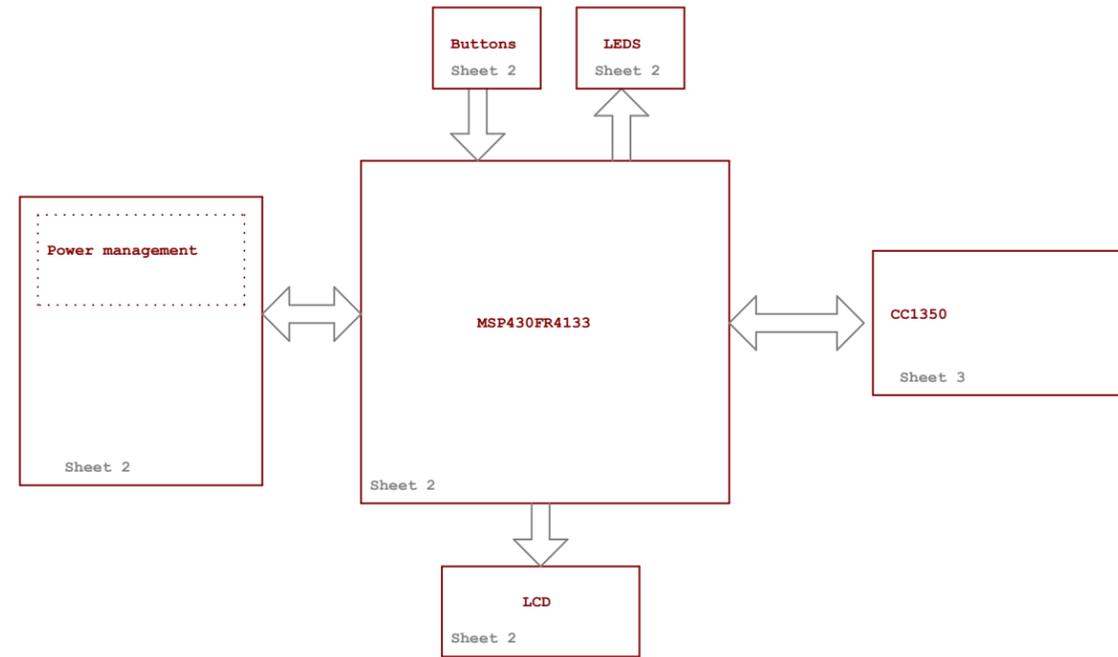


Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



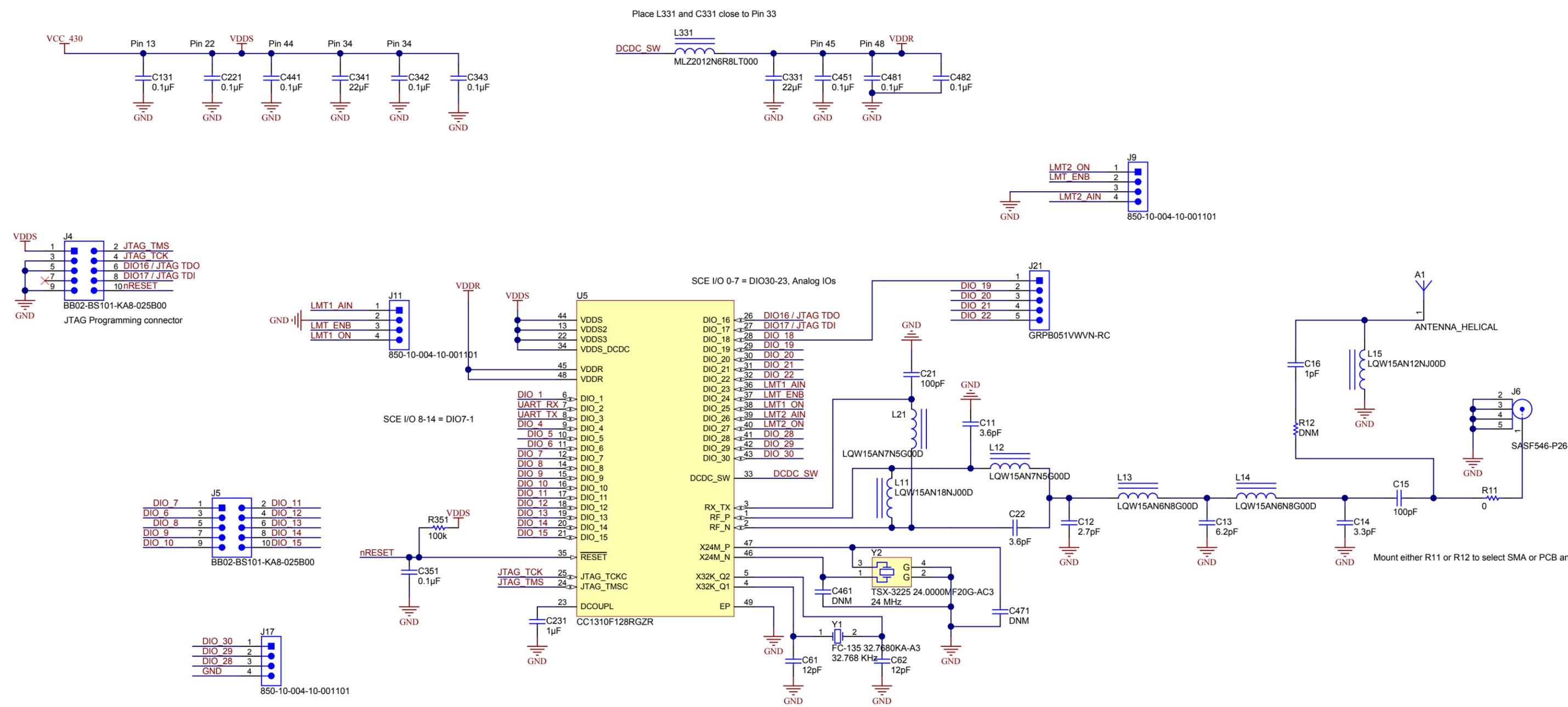
Texas Instruments

Milen Stefanov

1.0

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Orderable: N/A	Designed for: Public Release	Mod. Date: 10/18/2015	 http://www.ti.com © Texas Instruments 2015
TID #: TIDA-00838	Project Title: Heat Cost Allocator with wM-Bus @ 868MHz		
Number: TIDA-00838	Rev: E1	Sheet: 1 of 3	
SVN Rev: Version control disabled	Assembly Variant: 001		
Drawn By:	File: TIDA-00838_CoverSheet_SchDoc	Size: B	
Engineer: Milen Stefanov	Contact: http://www.ti.com/support		

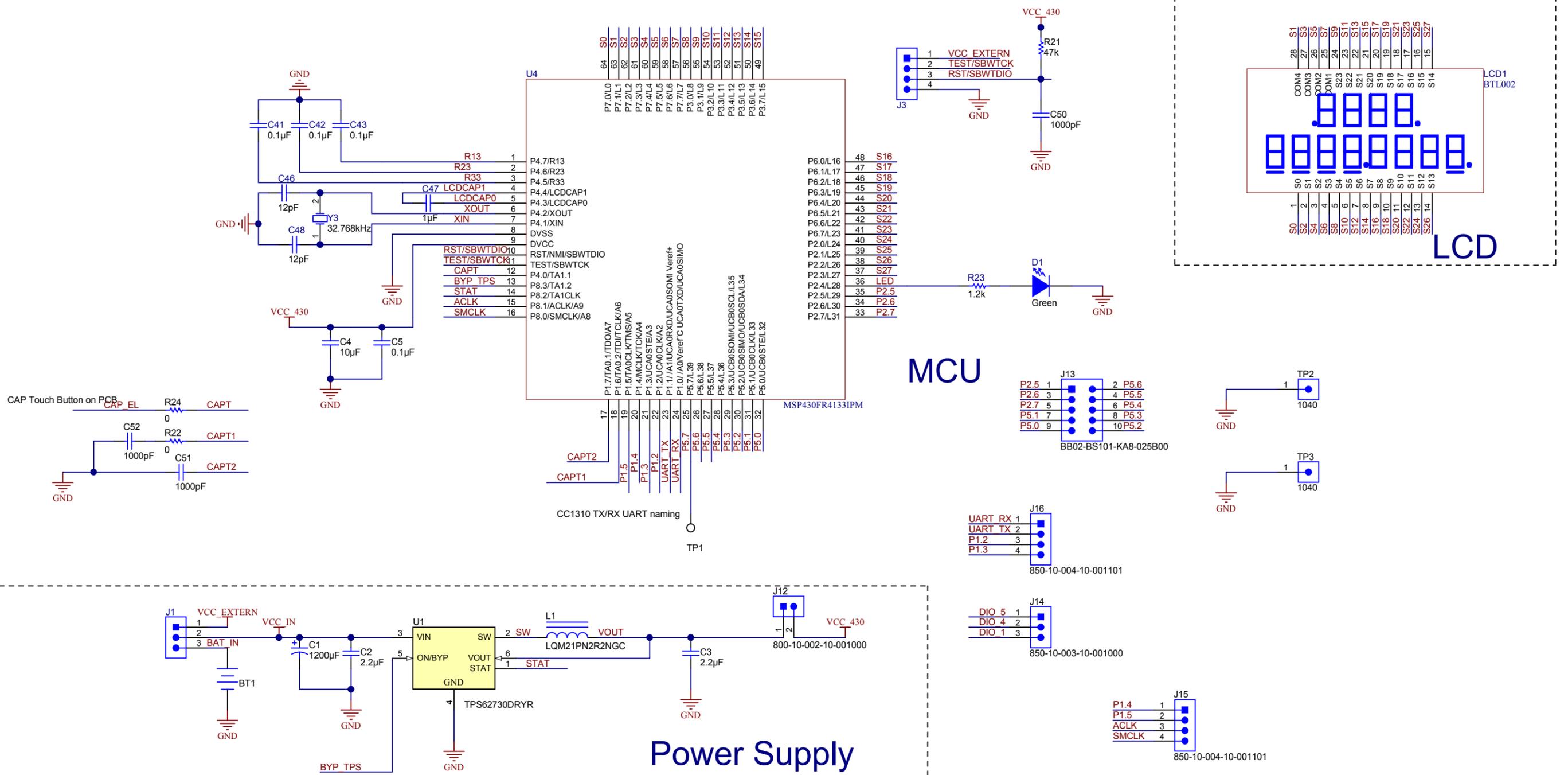


Place L331 and C331 close to Pin 33

Orderable: N/A	Designed for: Public Release	Mod. Date: 10/25/2015
TID #: TIDA-00838	Project Title: Heat Cost Allocator with wM-Bus @ 868MHz	
Number: TIDA-00838	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA-00838_RF.SchDoc	Size: B
Engineer: Milen Stefanov	Contact: http://www.ti.com/support	

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Do Not Mount: U1, L1, C2 and C3; add a wire from J1-2 to J12-2 (connect VCC_IN to VCC_430) to bypass TPS62730

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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/17/2015
TID #: TIDA-00838	Project Title: Heat Cost Allocator with wM-Bus @ 868MHz	
Number: TIDA-00838	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA-00838_MCU_SchDoc	Size: B
Engineer: Milen Stefanov	Contact: http://www.ti.com/support	



H1
NY PMS 440 0025 PH

H4
NY PMS 440 0025 PH

DNP FID1
DNP FID2
DNP FID3

PCB Number: TIDA-00838
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 10/28/2015	TEXAS INSTRUMENTS
TID #: TIDA-00838	Project Title: Heat Cost Allocator with wM-Bus @ 868MHz	Sheet: 3 of 3	
Number: TIDA-00838	Rev: E1	File: TIDA-00838_TID_Hardware.SchDoc	http://www.ti.com
SVN Rev: Version control disabled	Assembly Variant: 001	Contact: http://www.ti.com/support	© Texas Instruments 2015
Drawn By:	Engineer: Milen Stefanov		

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